c3PR: Mar Junge 408-730-8506, c 408-219-0101

Quik-Pak: Casey Krawiec: 858-674-4676 Promex: Rosie Medina 408-816-8035

For Immediate Release

Quik-Pak, Promex Combine Forces to Bring Wireless Medical Devices to Market Faster

IMAPS Advanced Packaging for Wireless Medical Devices Workshop Premier Sponsor Quik-Pak Launches Co-Exhibit with Parent Company Promex Industries, Inc.

San Diego, CA – January 27, 2016 – PRNewswire/iReach – Quik-Pak, a quick-turn prototype specialist for medical devices, is co-exhibiting with its parent company Promex Industries Inc., an electronic manufacturing services (EMS) provider that integrates conventional SMT with semiconductor microelectronic packaging and assembly. Together, the two companies bring complex RF and microwave wireless medical devices to market faster using Quik-Pak's wafer processing and IC packaging solutions and Promex's 35 years of engineering experience with complex assemblies.

"We offer the best of both worlds for the packaging and assembly of medical devices, including Class III implantable devices," said Quik-Pak Director of Sales and Marketing Casey Krawiec. "We offer device designers a time-to-market advantage with our high throughput, maximum-yield packaging solutions, plus high reliability through Promex's fully controlled process flows and deep engineering expertise."

The venue for the Quik-Pak/Promex exhibit is a technical workshop on *Advanced Packaging for Wireless Medical Devices* hosted by the International Microelectronics Assembly and Packaging Society (IMAPS). Convening in San Diego this week, the workshop is expected to draw experts in the fields of medicine, chemistry, RF and semiconductor packaging to discuss emerging packaging technologies for medical diagnostic devices.

Quik-Pak's IC packaging solutions for complex RF/MW medical devices include air cavity plastic QFN packages, over-molded plastic QFN/DFN packages, custom transfer molded packaging, and custom assembly for ceramic, laminate, COF and COB. Quik-Pak also offers assembly services from prototype design validation to full production, as well as wafer preparation services including dicing, backgrinding and pick and place. The company's 15,000 square foot facility includes fully automated equipment for high throughput and maximum yield. More information is available at www.icproto.com, or by calling 858-674-4676.

Promex specializes in engineering and proof of concept through production of Class III implantable and other complex medical devices. The company operates a 30,000 square foot assembly facility in Silicon Valley with RoHS-optimized surface mount technology (SMT), Class 100 and 1000 clean rooms and fully controlled process flows for high reliability. Together, the Promex and Quik-Pak facilities are ISO 13485:2003 and ISO 9001:2008 certified, ITAR registered and compliant to regulatory requirements for medical products. More information is available at www.promex-ind.com or by calling 408-496-0222.

Our full suite of IC packaging services can get your wireless medical devices to market FASTER!

C-1-00



IC packaging solutions for complex RF/MW medical devices

- · Air cavity plastic QFN packages Over-molded plastic QFN/DFN
- packages
 Custom transfer molded packaging
- · Ceramic, laminate, COF, COB

Assembly services from prototype design validation to full production

- · Wire bonding
- · Flip chip Air cavity lidding
 Encapsulation
 Marking

Wafer prep from quick-turn runs to volume production

- Wafer dicing
- · Wafer backgrinding
- Pick and place
 Fully automated equipment for high throughput and maximum yield

Engineering for complex assemblies

- 35 years of core-capability experience
 Packaging and manufacturing engineers on staff
- Proof of concept through production

manufacturing for complex

- RoHS optimized SMT lines
 Class 100 and Class 1000 cleanrooms
- Fully controlled process flows for high reliability
 Class III implantable devices are our









www.icproto.com 858-674-4676

Premier Sponsor

Promex

www.promex-ind.com 408-496-0222